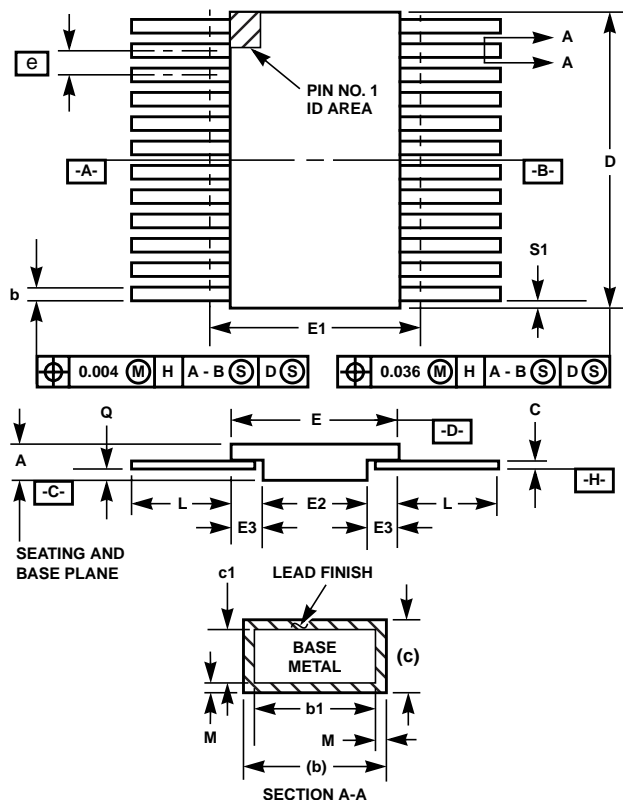


## Ceramic Metal Seal Flatpack Packages (Flatpack)



**K24.B**  
24 LEAD CERAMIC METAL SEAL FLATPACK PACKAGE

| SYMBOL | INCHES    |        | MILLIMETERS |       | NOTES |
|--------|-----------|--------|-------------|-------|-------|
|        | MIN       | MAX    | MIN         | MAX   |       |
| A      | 0.070     | 0.115  | 1.78        | 2.92  | -     |
| b      | 0.015     | 0.022  | 0.38        | 0.56  | -     |
| b1     | 0.015     | 0.019  | 0.38        | 0.48  | -     |
| c      | 0.004     | 0.009  | 0.10        | 0.23  | -     |
| c1     | 0.004     | 0.006  | 0.10        | 0.15  | -     |
| D      | 0.590     | 0.610  | 14.99       | 15.49 | 3     |
| E      | 0.490     | 0.510  | 12.45       | 12.95 | -     |
| E1     | -         | 0.520  | -           | 13.20 | 3     |
| E2     | 0.370     | 0.390  | 9.40        | 9.91  | -     |
| E3     | 0.030     | -      | 0.76        | -     | 7     |
| e      | 0.050 BSC |        | 1.27 BSC    |       | -     |
| k      | -         | -      | -           | -     | -     |
| L      | 0.330     | 0.350  | 8.38        | 8.89  | -     |
| Q      | 0.026     | 0.045  | 0.66        | 1.14  | 8     |
| S1     | 0.005     | -      | 0.13        | -     | 6     |
| M      | -         | 0.0015 | -           | 0.04  | -     |
| N      | 24        |        | 24          |       | -     |

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**NOTES:**

1. Index area: A notch or a pin one identification mark shall be located adjacent to pin one and shall be located within the shaded area shown. The manufacturer's identification shall not be used as a pin one identification mark. Alternately, a tab (dimension k) may be used to identify pin one.
2. If a pin one identification mark is used in addition to a tab, the limits of dimension k do not apply.
3. This dimension allows for off-center lid, meniscus, and glass overrun.
4. Dimensions b1 and c1 apply to lead base metal only. Dimension M applies to lead plating and finish thickness. The maximum limits of lead dimensions b and c or M shall be measured at the centroid of the finished lead surfaces, when solder dip or tin plate lead finish is applied.
5. N is the maximum number of terminal positions.
6. Measure dimension S1 at all four corners.
7. For bottom-brazed lead packages, no organic or polymeric materials shall be molded to the bottom of the package to cover the leads.
8. Dimension Q shall be measured at the point of exit (beyond the meniscus) of the lead from the body. Dimension Q minimum shall be reduced by 0.0015 inch (0.038mm) maximum when solder dip lead finish is applied.
9. Dimensioning and tolerancing per ANSI Y14.5M - 1982.
10. Controlling dimension: INCH.